

110-43-328-10-001000

110-43-328-10-001000 Information

why relative contract	 110-43-328-10-001000 Mill-Max Manufacturing Corp. Connectors, Interconnects Sockets for ICs, Transistors CONN IC DIP SOCKET 28POS GOLD - For the pricing/inventory/lead time, please contact	
For Reference Only	us Website: https://www.heisener.com E-mail: salesdept@heisener.com	Request a Quote

Certified Quality

Heisener's commitment to quality has shaped our processes for sourcing, testing, shipping, and every step in between. This foundation underlies each component we sell.



110-43-328-10-001000 Specifications

Manufacturer Mill-Max Manufacturing Corp. Category Connectors, Interconnects Sockets for ICs, Transistors Sockets for ICs, Transistors Package - Series 110 Type DIP, 0.3" (7.62mm) Row Spacing Number of Positions or Pins (Grid) 28 (2 x 14), 16 Loaded Pitch - Mating 0.100" (2.54mm) Contact Finish - Mating Gold Contact Finish - Mating 30µin (0.76µm) Contact Material - Mating Beryllium Copper Mounting Type Through Hole Features Open Frame Pitch - Post Gold Contact Finish Thickness - Post Gold Contact Finish - Post Gold Contact Finish - Post Open Frame Contact Finish Thickness - Post Gold Contact Material - Post Gold Contact Material - Post			
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	Housing Material	Polycyclohexylenedimethylene Terephthalate (PCT), Polyester	
Report errors?	Operating Temperature	-55°C ~ 125°C	
			Report errors?

110-43-328-10-001000 Guarantees



Quality Guarantees

We provide 90 days warranty. * If the items you received were not in perfect quality, we would be responsible for your refund or replacement, but the items must be returned in their original condition.

SERVICE BUARANTEE

Service Guarantees

We guarantee 100% customer satisfaction. Our experienced sales team and tech support team back our services to satisfy all our customers.

110-43-328-10-001000 Payment Methods





If you have any question about 110-43-328-10-001000, please do not hesitate to contact us! Website: https://www.heisener.com E-mail: salesdept@heisener.com